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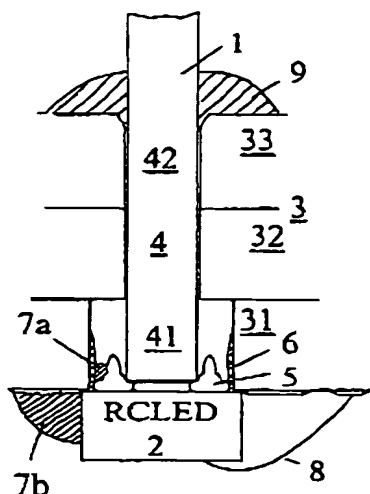
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(54) Title: ALIGNMENT OF AN OPTIC OR ELECTRONIC COMPONENT



(57) Abstract: A method and an arrangement for aligning at least one optic and/or electronic component (2) on a substrate (3) or a corresponding support structure, wherein the method comprises: arranging a hole (4) in the support structure; arranging at least three stud bumps (5) on the surface of the component (2); and arranging said stud bumps along the periphery of the hole (4) for alignment of the component (2) to the hole (4).

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